

Title (en)  
MODULAR PANEL FOR LAYING IN UNDERFLOOR AND WALL HEATING SYSTEMS AND THERMOCONDUCTIVE SHEETS FOR THE SAME

Title (de)  
MODULARE VERLEGEPLATTE ZUM VERLEGEN IN FUSSBODEN- ODER WANDHEIZSYSTEMEN UND WÄRMELEITBLECHE DAZU

Title (fr)  
PLAQUE A POSER MODULAIRE UTILISEE DANS DES SYSTEMES DE CHAUFFAGE PAR PLANCHER OU PAR MUR ET TOLES THERMOCONDUCTRICES ASSOCIEES

Publication  
**EP 1332318 A1 20030806 (DE)**

Application  
**EP 01992865 A 20011106**

Priority

- DE 10054880 A 20001106
- DE 20021121 U 20001213
- DE 20021942 U 20001223
- EP 0112839 W 20011106

Abstract (en)

[origin: WO0237032A1] The invention relates to a modular panel (100; 200) consisting of thermal insulation material for laying in underfloor or wall heating systems. Said panel comprises a flat rectangular base body (1) and cavities for accommodating thermal conduits (3). The cavities are configured as a grid-type arrangement of channels (2), consisting of several intersecting, rectilinear channels (2.1.1, ..., 2.1.n; 2.2.1, ..., 2.2.n) that run parallel to the lateral edges, several rectilinear channels (2.3.1, ..., 2.3.n; 2.4.1, ..., 2.4.n) that likewise intersect and run diagonally and at least two rows (R1, R2) of arched channel sections (2.5.1, ..., 2.5.n), positioned mirror-symmetrically, the vertexes (S) of said arched channel sections facing towards the lateral edges and the respective ends (18.1, 18.2) of said sections being connected to the rectilinear channels. The intersecting channels (2.1.1, ..., 2.1.n; 2.2.1, ..., 2.2.n) that run parallel to the lateral edges (11.1, ..., 11.4) are located at equal distances (A) from one another. The channels running diagonally intersect at intersection points (P1), said channels are equidistant (D) - measured diagonally - from the intersection points (P2) of the channels that run parallel to the lateral edges. The invention also comprises a surface heating system, such as an underfloor heating system, containing at least one modular panel and at least one thermoconductive sheet element.

IPC 1-7  
**F24D 3/14**

IPC 8 full level  
**F24D 3/14** (2006.01)

CPC (source: EP)  
**F24D 3/14** (2013.01); **F24D 3/142** (2013.01); **F24D 3/148** (2013.01); **F28F 2210/10** (2013.01); **Y02B 30/00** (2013.01)

Citation (search report)  
See references of WO 0237032A1

Designated contracting state (EPC)  
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)  
**WO 0237032 A1 20020510**; AU 1828502 A 20020515; EP 1332318 A1 20030806

DOCDB simple family (application)  
**EP 0112839 W 20011106**; AU 1828502 A 20011106; EP 01992865 A 20011106